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# TABLE OF CONTENTS

## 1A: Device Testing

### **1A.1 Sensor Gap TLP: Expanding Time Resolution and Pulse Duration Beyond Conventional Values of Standard and Very Fast Transmission Line Pulsing...1**

Dennis Helmut, Gerhard Groos, University of the Bundeswehr Munich

### **1A.2 ESD Stress Data Analysis with Machine Learning: A Case Study...12**

Caige Middaugh, Mehrdad Nourani, University of Texas at Dallas; Charvaka Duvvury, Joe Schichl, iT2 Technologies

### **1A.3 Novel ESD Characterization Method for Bipolar Devices Using a Combined TLP System with Dynamic Base Bias...21**

Filippo Magrini, Bernhard Stein, Michael Ammer, Gabriel Cretu, Infineon Technologies

### **1A.4 Impact of a Deep Junction Depth Coupled with a Short Channel Length on the ESD Robustness of a Grounded Gate nMOS Clamp...27**

Casey Hopper, Antonio Gallerano, Raj Sankaralingam, Analog Technology Development, Texas Instruments

### **1A.5 Discharge Waveforms of Emulated Die-to-Die ESD Discharges...35**

David Johnsson, HPPI GmbH; Pasi Tamminen, Danfoss Oy; Toni Viheriäkoski, Cascade Metrology Oy; Harald Gossner, Intel Cooperation

### **1A.6 Voltage to Current Correlation for CDM Testing...44**

Lena Zeithoefler, Theresa Lutz, Friedrich zur Nieden, Kai Esmark, Reinhold Gaertner, Infineon Technologies AG

### **1A.7 Study of Frequency Response of CDM Setup...54**

Jared R. Floyd, Wei Huang, Li Shen, Hossein R. Varnousafaderani, Matthew Drallmeier, ESDEMC Technology LLC

## 1B: EMC

### **1B.1 IEC ESD Co-Design Methodology for On-Chip Protection at High Voltage Transceivers...60**

Dimitrios Kontos, Wensong Chen, Vladislav Vashchenko, Analog Devices Inc.

### **1B.2 On the Safety Distance to Avoid Transient Latch-up During System Level ESD Stress...68**

Guido Quax, NXP Semiconductors

## **2A: GaN**

### **2A.1 Understanding Temperature Dependence of ESD Reliability in AlGaIn/GaN HEMTs...78**

Mohammad Ateeb Munshi, Mehak Ashraf Mir, Rasik Malik, Vipin Joshi, Rajarshi Chaudhuri, Zubear Khan, Mayank Shrivastava, Indian Institute of Science

### **2A.2 Interplay of Surface Passivation and Electric Field in Determining ESD Behavior of p-GaN Gated AlGaIn/GaN HEMTs...83**

Rasik Rashid Malik, Avinas N Shaji, Jayshree, Zubear Khan, Madhura Bhattacharya, Mohammad Ateeb Munshi, Rajarshi R. Chaudhuri, Vipin Joshi, Mayank Shrivastava, Indian Institute of Science

### **2A.3 Solutions to Improve HBM ESD Robustness of GaN RF HEMTs...90**

Abhinay Sandupatla, Shih-Hung Chen, Nadine Collaert, imec; Nikhil Mane, Nilam Pradhan, MIT-World Peace University; Bertrand Parvaris, imec, VUB Brussels

## **2B: Automotive**

### **2B.1 Complementary HV Dual Direction SCR Design Strategy...96**

Vladislav Vashchenko, Hossein Sarbishaei, Wensong Chen, Analog Devices Corp; Andrei Shibkov, Angstrom Design Automation LLC

### **2B.2 Electro-Thermal Mixed-Mode Analysis of HV Complementary DD-SCR's...103**

Andrei Shibkov, Angstrom Design Automation; Vladislav Vashchenko, Analog Devices, Inc.

## **3A: Emerging Technologies**

### **3A.1 Impact of Backside Power Delivery Network with Buried Power Rails on Latch-up Immunity in DTCO/STCO...110**

Kateryna Serbulova, Guido Groeseneken, KU Leuven, imec; Shih-Hung Chen, Geert Hellings, Anabela Veloso, Anne Jourdain, Jo De Boeck, Eugenio Dentoni Litta, Naoto Horiguchi, imec

### **3A.2 High Thermal Conductive Graphene-Based Composites and its Controllable ESD Application on Device Packaging...116**

Rong-Teng Lin, Bi-Xian Wu, Yun-Hong Yang, Teng-Chin Hsu, Chia-Lien Chao, Yu-Chiao Chang, Chiao-Jung Su, Chien-Hao Liu, Tzu-Hsuan Chang, National Taiwan University; Jam-Wem Lee, Kuo-Ji Chen, Wun-Jie Lin, TSMC

## **4A: Communications**

### **4A.1 Distributed Protection for High-Speed Wireline Receivers...122**

Matt Drallmeier, Elyse Rosenbaum, University of Illinois Urbana-Champaign

### **4A.2 Consideration Based on ESD Applied Waveform in High-Speed IF Using T-Coil (RCJ Best Paper)...131**

Teruo Suzuki, Hideki Kano; Socionext Inc.

### **4A.3 Fast Transient ESD Protection at RF Pins...139**

Christoph Eichenseer, Gernot Langguth, Reinhold Gaertner, Friedrich zur Nieden, Lena Zeitlhofer, Stefan Kokorovic, Infineon Technologies AG

## **5A: Device Testing**

### **5A.1 A Combined Model for Transient and Self-Heating of Snapback Type ESD Protection Devices...147**

Xin Yan, Seyed Mostafa Mousavi, Li Shen, Yang Xu, Wei Zhang, Daryl G. Beetner, EMCLAB, Missouri University of Science and Technology; Sergej Bub, Steffen Holland, Nexperia Germany GmbH; David Pommerenke, Technical University Graz

### **5A.2 A Versatile Behavioral Snapback ESD Model Incorporating Transient Effects and Failure Detection...154**

Michael Ammer, Christian Russ, Infineon Technologies AG

### **5A.3 A Hybrid Finite Difference Model for Open Base Transistors with Kirk Effect...162**

Steffen Holland, Hans-Martin Ritter, Taimoor Ahmed, Nexperia Germany GmbH

### **5A.4 Physics-Based Compact Model of N-Well ESD Diodes...169**

Shudong Huang, Elyse Rosenbaum, University of Illinois at Urbana-Champaign

### **5A.5 Effective ESD Design Through PERC Programming...175**

Kuo-Hsuan Meng, Michael Khazhinsky, Jeremy C. Smith, Silicon Labs

## **M1 & M2: Manufacturing**

### **M1.1 Die-to-Die ESD Discharge Current Analysis...185**

Pasi Tamminen, Danfoss; Toni Viheriäkoski, Cascade Metrology

### **M1.2 ESD Mitigation for 3D IC Hybrid Bonding...195**

Shih-Hsiang Lin, Marko Simicic, Nicolas Pantano, Shih-Hung Chen, Philippe Roussel, Geert Van der Plas, Erik Beyne, Piet Wambacq, imec

### **M1.3 Alternative Measurement Methodology for Fast Switching AC Ionizer Offset Voltage Measurement...204**

Joshua Yoo, Core Insight, Inc.; Arnold Steinman, Electronics Workshop

### **M2.1 ESD Risk Assessment for Devices on Printed Circuit Boards...212**

Reinhold Gaertner, Kai Esmark, Theresa Lutz, Friedrich zur Nieden, Lena Zeitlhöfler, Infineon Technologies AG

### **M2.2 Electrostatic Discharge Characteristics of Polymer Films...221**

Toni Viheriäkoski, Cascade Metrology; Jukka Hillberg, Cargill; Pasi Tamminen, Danfoss

### **M2.3 ESD Process Assessment of 2.5D and 3D Bonding Technologies...229**

Marko Simicic, Frank Gijbels, Serena Iacovo, Shih-Hung Chen, Geert Van der Plas and Eric Beyne, imec

## **Invited Paper**

### **IP.1 Automotive Semiconductor Test: Challenges and Solutions Towards Zero Defect Quality...236**

Chen He, NXP Semiconductors

### **IP.2 CAD-Based ESD Design Methodology is Critical to Emerging Technologies...247**

Zijin Pan, Weiquan Hao, Xunyu Li, Runyu Miao, Albert Wang, University of California

# Workshops

Workshops Chair – James DiSarro, Texas Instruments

## **Clearing the Air (Presentation and Interactive Workshop)...257**

Moderator: *Hans Kunz, Texas Instruments*

## **ESD EDA - What Can be Done Now and in the Future? (World Café Format)...258**

Moderator: *Michael Khazhinsky, Silicon Laboratories*

## **Hand Tools - Understanding and Applying Resistance Measurement Techniques...259**

Moderators: *Christopher Almeras, Raytheon; Charles McClain, Micron*

## **Beyond the ESD Design Manual: What is an Optimal Foundry ESD Design Infrastructure? (Town Hall format)...260**

Moderator: *Efraim Aharoni, Tower Semiconductor*

Panelists: *Jam-Wem Lee, TSMC; Michael Stockinger, NXP Semiconductors*

## **The Role of Standards in Innovation...261**

Moderator: *Ann Concannon, Texas Instruments*

Panelists: *Wolfgang Stadler, Intel Germany Services GmbH; Julie Van Campen, NASA; Keith Peterson, Missile Defense Agency*

## **EOS/ESD Association, Inc. Technology Roadmap (Presentation & Interactive Workshop)...262**

Moderator: *Harald Gossner, Intel Germany Services GmbH; Mirko Scholz, Infineon Technologies AG*

## **Biographies...263**

## **Past Awards and Presentations...277**

## **2023 Exhibitors List...N/A**

## **Technical Program Committee...287**